

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT2953862

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YUN-WEI CHENG	06/20/2014
CHEN CHIU-JUNG	06/20/2014
VOLUME CHIEN	06/20/2014
KUO-CHENG LEE	06/27/2014
YUNG-LUNG HSU	07/03/2014
CHEN HSIN-CHI	07/04/2014
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14308760
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	214-651-5000
Email:	ipdocketing@haynesboone.com
Correspondent Name:	HAYNES AND BOONE, LLP IP SECTION
Address Line 1:	2323 VICTORY AVENUE
Address Line 2:	SUITE 700
Address Line 4:	DALLAS, TEXAS 75219
ATTORNEY DOCKET NUMBER:	24061.2877
NAME OF SUBMITTER:	DAVID M. O'DELL
SIGNATURE:	/David M. O'Dell/
DATE SIGNED:	07/25/2014

PATENT

Total Attachments: 3

source=2877-assignment#page1.tif

source=2877-assignment#page2.tif

source=2877-assignment#page3.tif

Docket No.: 2014-0257-C / 24061.2877
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- (1) Yun-Wei Cheng of 9F.-1, No. 127, Sec. 3, Muzha Rd., Wenshan Dist. Taipei City, Taiwan, R.O.C. 116
- (2) Chen Chiu-Jung of No. 283, Xinglong Rd., South Dist. Tainan City, Taiwan, R.O.C. 70261
- (3) Volume Chien of No. 31, Aly. 14, Ln. 89, Dongxing 6th St., Xinying Dist. Tainan City, Taiwan, R.O.C. 730
- (4) Kuo-Cheng Lee of No. 31, Dongqiao 8th St., Yongkang Dist. Tainan City, Taiwan, R.O.C. 710
- (5) Yung-Lung Hsu of No. 67, Lane 199, Yu-De Rd., North District Tainan, Taiwan, R.O.C.
- (6) Chen Hsin-Chi of No. 51, Ln. 239, Dingmei 3rd St., West Central Dist. Tainan City, Taiwan, R.O.C. 700

have invented certain improvements in

FORMATION OF BURIED COLOR FILTERS IN A BACK SIDE ILLUMINATED IMAGE SENSOR WITH AN ONO-LIKE STRUCTURE

for which we have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and
 X filed on June 19, 2014 and assigned application number 14/308,760; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a

Docket No.: 2014-0257-C / 24061.2877
Customer No.: 42717

filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Yun-Wei Cheng

Residence Address: 9F.-1, No. 127, Sec. 3, Muzha Rd., Wenshan Dist.
Taipei City, Taiwan, R.O.C. 116

Dated: 2014/6/20

Yun Wei Cheng
Inventor Signature

Inventor Name: Chen Chiu-Jung

Residence Address: No. 283, Xinglong Rd., South Dist.
Tainan City, Taiwan, R.O.C. 70261

Dated: 2014/6/20

Chen Chiu-Jung
Inventor Signature

Inventor Name: Volume Chien

Residence Address: No. 31, Aly. 14, Ln. 89, Dongxing 6th St., Xinying Dist.
Tainan City, Taiwan, R.O.C. 730

Dated: 2014/6/20

Volume Chien
Inventor Signature

Docket No.: 2014-0257-C / 24061.2877
Customer No.: 42717

Inventor Name: Kuo-Cheng Lee

Residence Address: No. 31, Dongqiao 8th St., Yongkang Dist.
Tainan City, Taiwan, R.O.C. 710

Dated: 2014.6.27

Kuo-Cheng Lee
Inventor Signature

Inventor Name: Yung-Lung Hsu

Residence Address: No. 67, Lane 199, Yu-De Rd., North District
Tainan, Taiwan, R.O.C.

Dated: 8/3/2014

Yung-Lung Hsu
Inventor Signature

Inventor Name: Chen Hsin-Chi

Residence Address: No. 51, Ln. 239, Dingmei 3rd St., West Central Dist.
Tainan City, Taiwan, R.O.C. 700

Dated: 2014 Jul. 04.

Chen Hsin-Chi
Inventor Signature